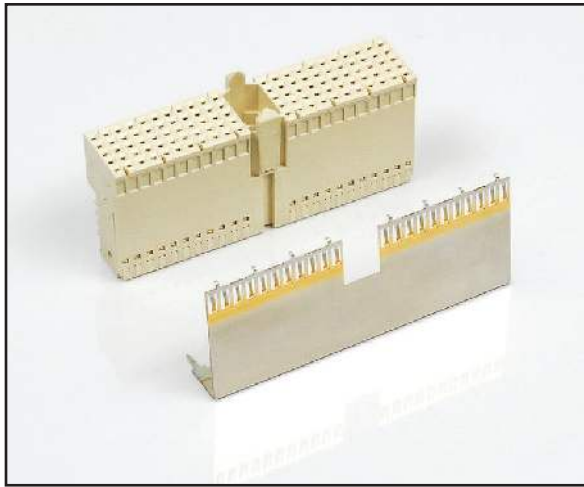


# 3M™ CP2 Press-Fit Socket

2 mm Type A 110 Signal Contacts Right Angle

CP2 Series



- 25mm basic system unit
- 50mm module
- Designed according to IEC 61076-4-101 and IEC 60352-5 Standards
- 2 mm grid spacing allows for high signal density at low cost
- “Eye of the Needle” compliant pin press-fit design reduces manufacturing time and cost
- Additional grounding row available for improved ground bounce and EMI immunity
- Mates with 5 row 3M™ MetPak™ HM, and CP2 headers
- End-to-end stackable with 5 row 3M™ MetPak™ HSHM, HM, and CP2 sockets
- See Regulatory Information Appendix (RIA) for chemical compliance information

Date Modified: February 15, 2008

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Sheet 1 of 2

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## Physical

### Insulation:

Material: High Temperature Thermoplastic (LCP)

Flammability: UL94V-0

### Contact:

Material: Copper Alloy

Plating: See Ordering Information

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## Mechanical

Mating Force:  $\leq 0.75\text{N/PIN}$

Withdrawl Force:  $\geq 0.15\text{N/PIN}$

Mating and Un-mating Operations: 50

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## Electrical

Contact Resistance:  $\leq 20\text{ m}\Omega$

Insulation Resistance:  $\geq 10,000\text{ M}\Omega$

Test Voltage:  $750\text{ VAC}_{\text{RMS}}$

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## Environmental

Temperature Ratings:  $-55^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$

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## PCB Data

Recommended PCB Plated Through Hole:  $\Phi 0.6\pm 0.05\text{ mm}$

Drill Hole Diameter:  $\Phi 0.7\pm 0.02\text{ mm}$

Hole platings: Cu 25~50  $\mu\text{m}$ , Sn or SnPb < 10  $\mu\text{m}$

PCB thickness: 1.4-4.2 mm

Press-In Force:  $\leq 204\text{N/pin}$  on nominal hole diameter

Retention Force:  $\geq 13.5\text{N/pin}$  on nominal hole diameter

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**3M**

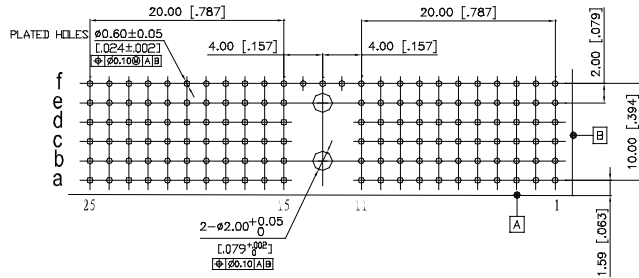
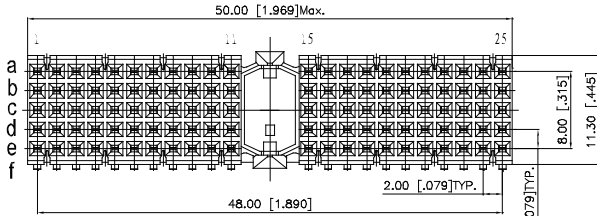
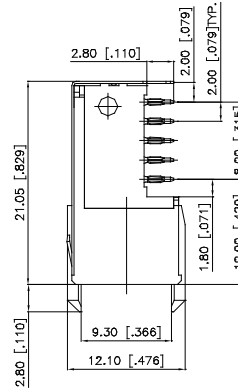
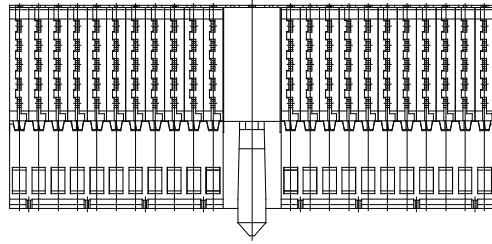
Electronic Solutions Division  
Interconnect Solutions  
<http://www.3M.com/interconnects/>

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# 3M™ CP2 Press-Fit Socket

2 mm Type A 110 Signal Contacts Right Angle

CP2 Series



Recommended PCB Layout

| Tolerance Unless Noted |           |     |      |
|------------------------|-----------|-----|------|
|                        | mm [Inch] |     |      |
|                        | 0.        | .0  | .00  |
| mm                     | 1         | 0.3 | 0.13 |

[ ] Dimensions for Reference only

## Ordering Information

### CP2-SA110-X1-XXXX

Shield Options  
 G= Upper Shield  
 Blank= No Shield

Plating Options

- TG30= 30~40 μm Gold Contact Area  
 100~200 μm Bright Tin-Lead  
 50~80 μm Nickel Underplate  
 (RIA E2 & C2 apply)
- FJ= 10~20 μm Gold Contact Area  
 200~300 μm Matte Tin  
 50~80 μm Nickel Underplate  
 (RIA E1 & C1 apply)
- KR= 30~40 μm Gold Contact Area  
 200~300 μm Matte Tin  
 50~80 μm Nickel Underplate  
 (RIA E1 & C1 apply)

• This diagram serves only for Part Number descriptive definitions.

PLEASE CONTACT YOUR LOCAL SALES REPRESENTATIVE FOR CUSTOMER SPECIFIC PRODUCT CONFIGURATIONS.

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 Sheet 2 of 2



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